

REMARKS

This application has been reviewed in light of the Office Action dated July 22, 2009.

Claims 1-18 are in the application; claims 4 and 7-18 have been withdrawn from consideration. Claims 1-3, 5 and 6 are presented for examination. Claim 1 has been amended. Claim 1 is the only independent claim now under consideration. Favorable review is respectfully requested.

Claim 1 is directed to a semiconductor device package including a molding compound forming a portion of package side faces, and a lead frame having a plurality of posts at the perimeter of the package. Claim 1 has been amended to recite further details regarding the molding compound and the posts at the package side faces. Specifically, claim 1 now recites that the molding compound is coplanar with side surfaces of the posts at the package side faces, and two package side faces meet to form a square corner at each of four corner regions of the package. These features are clearly shown in the specification in FIGS. 1 and 7 (perspective view) and FIGS. 3, 4, 10, and 11 (plan view); see also paragraphs 0034 and 0049 of the published application, with reference to FIG. 5i.

Claims 1-3, 5 and 6 were rejected under 35 U.S.C. § 102(b) as anticipated by Yamaguchi (JP 200012420). The applicants respectfully submit that amended independent claim 1 is patentably distinct from the cited art, for the following reasons.

Yamaguchi is understood to disclose a resin-sealed semiconductor device 24 and lead frame, where portions 27 of the lead frame are arranged around a die pad 17 (FIG. 6). The sealing resin 26 extends between the lead frame portions and forms a shaped package (FIGS. 4, 5, 9, 10 and 11). It is noteworthy that in these figures, the resin-molded shape has chamfered corners. Those skilled in the art recognize that this indicates singulation of the devices by a punching operation. The device package of claim 1, by contrast, has side faces that meet to form a square corner in the four corner regions, and has the molding compound coplanar with side surfaces of the posts at the package side faces. This is consistent with singulation by a sawing operation.

Yamaguchi appears to disclose an arrangement (FIGS. 7 and 8) where an individual resin-sealed unit has square corners; in these arrangements, the exposed portions 27 of the lead frame clearly protrude from the resin 26, and are not coplanar with the side faces of the unit (or for that matter with any faces, as shown in FIGS. 6 and 12).

Yamaguchi fails to teach or suggest a device package having both square corners and posts coplanar with the molding compound at the side surfaces. Accordingly, amended claim 1 is not anticipated by the reference.

The other claims now pending in the application are dependent from the independent claim discussed above and are believed to be patentable for the same reasons. Since each dependent claim is directed to a separate aspect of the invention, however, the individual consideration of each claim on its own merits is respectfully requested.

In view of the foregoing amendments and remarks, favorable consideration and early passage to issue of the application are respectfully requested.

No fees are believed to be due. The Commissioner is nevertheless authorized to charge any required fees to Deposit Account No. 23-1665.

The applicants' undersigned attorney may be reached by telephone at 212-551-2625. All correspondence should continue to be directed to the address given below, which is the address associated with Customer Number 27267.

Respectfully submitted,



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